

PS8101

1 Mbps, HIGH CMR ANALOG OUTPUT TYPE 5-PIN SOP (SO-5) PHOTOCOUPLER R08DS0138EJ0100 Rev.1.00 Oct.29.2018

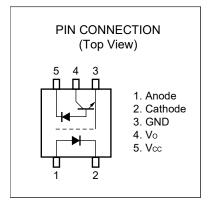
DESCRIPTION

The PS8101 is an optically coupled isolator containing an AlGaAs LED on the light emitting diode (input side) and a PIN photodiode and a high-speed amplifier transistor on the output side on one chip.

This is a plastic SOP (Small Out-line Package) type for high density applications.

FEATURES

- High common mode transient immunity (CM_H, CM_L = ± 15 kV/ μ s MIN.)
- Small package (SO-5)
- High supply voltage ($V_{CC} = 35 \text{ V}$)
- High isolation voltage (BV = 3 750 Vr.m.s.)
- High-speed response ($t_{PHL} = 0.8 \mu s \text{ MAX.}$, $t_{PLH} = 1.2 \mu s \text{ MAX.}$)
- Ordering number of taping product: PS8101-F3: 2 500 pcs/reel
- Pb-Free product
- · Safety standards
 - UL approved: UL1577, Single protection
 - CSA approved: CAN/CSA-C22.2 No. 62368-1, Basic insulation
 - VDE approved: DIN EN 60747-5-5 (Option)

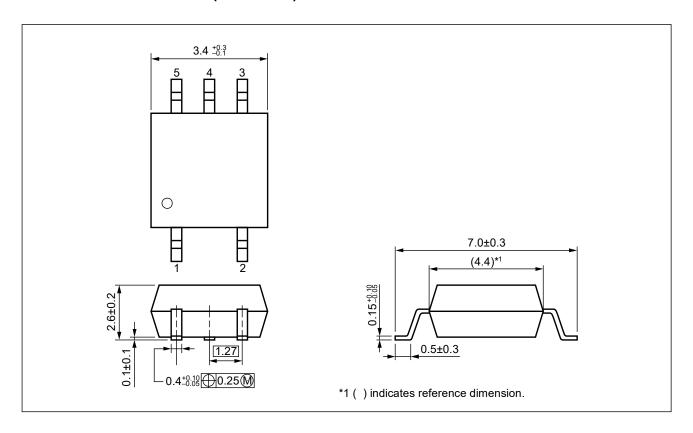


APPLICATIONS

- Computer and peripheral manufactures
- General purpose inverter
- Substitutions for relays and pulse transformers
- Power supply

Start of mass production Jul.2007

PACKAGE DIMENSIONS (UNIT: mm)

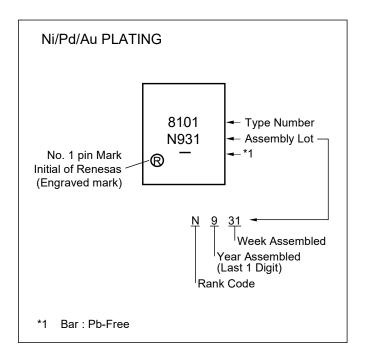


Weight: 0.08g (typ.)

PHOTOCOUPLER CONSTRUCTION

Parameter	PS8101
Air Distance (MIN.)	4.2 mm
Creepage Distance (MIN.)	4.2 mm
Isolation Distance (MIN.)	0.2 mm

MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification			Application Part Number*1
PS8101	PS8101-AX	Pb-Free	20 pcs (Tape 20 pcs cut)	Standard products	PS8101
PS8101-F3	PS8101-F3-AX	(Ni/Pd/Au)	Embossed Tape 2500 pcs/reel	(UL, CSA approved)	
PS8101-V	PS8101-V-AX]	20 pcs (Tape 20 pcs cut)	UL, CSA,	
PS8101-V-F3	PS8101-V-F3-AX		Embossed Tape 2 500 pcs/reel	DIN EN 60747-5-5 approved	"

Notes: *1. For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

	Parameter	Symbol	Ratings	Unit
Diode	Forward Current	lF	25	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation*1	PD	45	mW
Detector	Supply Voltage	Vcc	35	V
	Output Voltage	Vo	35	V
	Output Current	lo	8.0	mA
	Power Dissipation *2	Pc	100	mW
Isolation V	/oltage ^{*3}	BV	3 750	Vr.m.s.
Operating Ambient Temperature		TA	−55 to +100	°C
Storage T	emperature	T _{stg}	−55 to +125	°C

Notes: *1. Reduced to 0.45 mA/°C at T_A = 25°C or more.

^{*2.} Reduced to 1.00 mW/°C at T_A = 25°C or more.

^{*3.} AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output. Pins 1-2 shorted together, 3-5 shorted together.

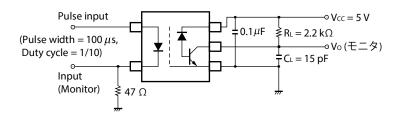
ELECTRICAL CHARACTERISTICS (T_A = 25°C, unless otherwise specified)

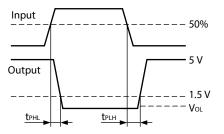
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 16 mA		1.7	2.2	V
	Reverse Current	I _R	V _R = 3 V			10	μA
	Forward Voltage Temperature Coefficient	ΔVε/ΔΤΑ	I _F = 16 mA		-2.1		mV/°C
	Terminal Capacitance	Ct	V = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Current	Іон (1)	$I_F = 0 \text{ mA}, V_{CC} = V_0 = 5.5 \text{ V}$		3	500	nA
	High Level Output Current	Іон (2)	I _F = 0 mA, V _{CC} = V _O = 30 V			100	μА
	Low Level Output	V _{OL}	I _F = 16 mA, V _{CC} = 4.5 V,		0.1	0.4	V
	Voltage		lo = 1.2 mA				
	Low Level Supply	Iccl	I _F = 16 mA, V _O = open,		50		μA
Current	Current		V _{CC} = 30 V				
	High Level Supply Current	Іссн	$I_F = 0$ mA, $V_O = open$, $V_{CC} = 30$ V		0.01	2	
Coupled	Current Transfer Ratio*1	CTR	I _F = 16 mA, V _{CC} = 4.5 V,V _O = 0.4 V	15	20	35	%
	Isolation Resistance	R _{I-O}	V _{I-O} = 1 kV _{DC} , RH = 40 to 60%	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1 MHz		0.4		pF
	Propagation Delay Time $(H \rightarrow L)^{*2}$	t _{PHL}	I_F = 16 mA, V_{CC} = 5 V, R_L = 2.2 k Ω , C_L = 15 pF		0.5	0.8	μS
	Propagation Delay Time $(L \rightarrow H)^{*2}$	t _{PLH}			0.6	1.2	
	Common Mode Transient Immunity at High Level Output*3	СМн	I_F = 0 mA, V_{CC} = 5 V, R_L = 4.1 kΩ, V_{CM} = 1.5 kV	15			kV/μs
	Common Mode Transient Immunity at Low Level Output*3	CML	I _F = 16 mA, V _{CC} = 5 V, R _L = 4.1 kΩ, V _{CM} = 1.5 kV	-15			

Notes:*1. CTR rank

K : 20 to 35 (%) N : 15 to 35 (%)

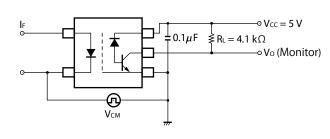
*2. Test circuit for propagation delay time

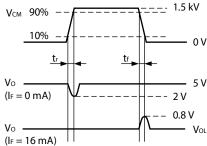




Remark C_L includes probe and stray wiring capacitance.

*3. Test circuit for common mode transient immunity

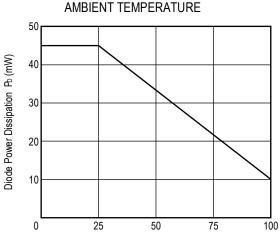




USAGE CAUTIONS

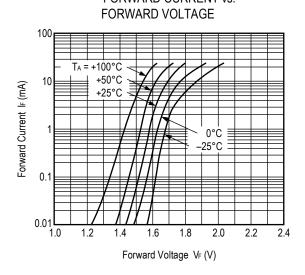
- 1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
- 2. By-pass capacitor of more than 0.1 μ F is used between V_{CC} and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
- 3. Avoid storage at a high temperature and high humidity.
- 4. Do not use adhesives or coating materials including halogens to fix this device.

TYPICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

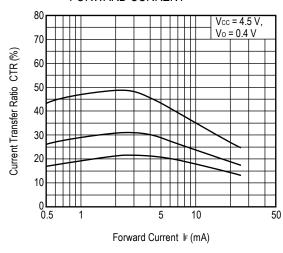


DIODE POWER DISSIPATION vs.

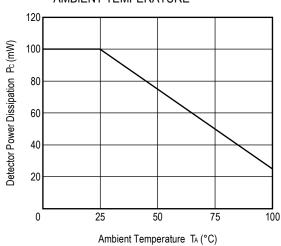




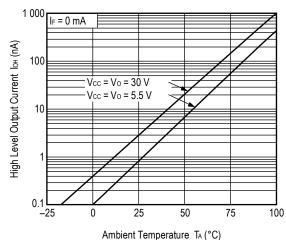
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



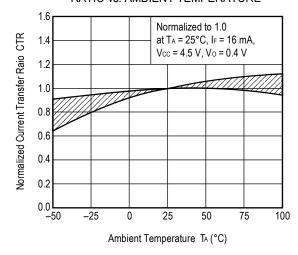
DETECTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE



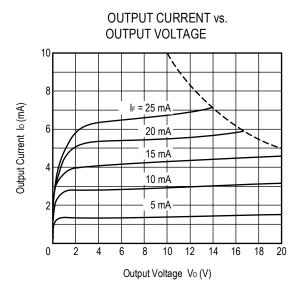
HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE



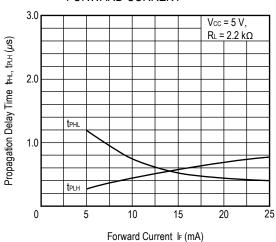
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



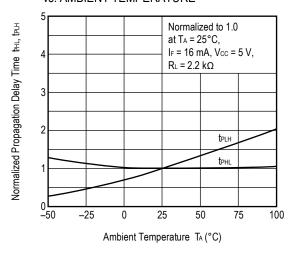
Remark The graphs indicate nominal characteristics.



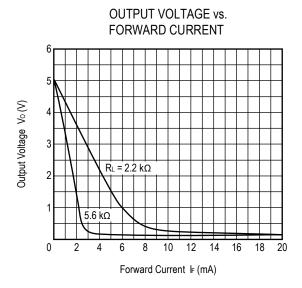




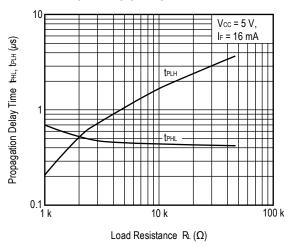
NORMALIZED PROPAGATION DELAY TIME vs. AMBIENT TEMPERATURE



Remark The graphs indicate nominal characteristics.

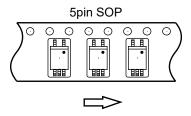


PROPAGATION DELAY TIME vs. LOAD RESISTANCE

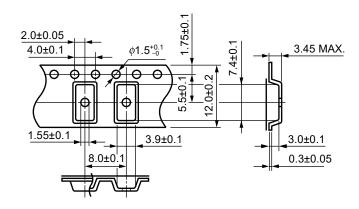


TAPING SPECIFICATIONS (UNIT: mm)

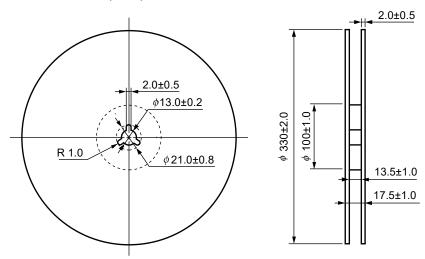




Outline and Dimensions (Tape)

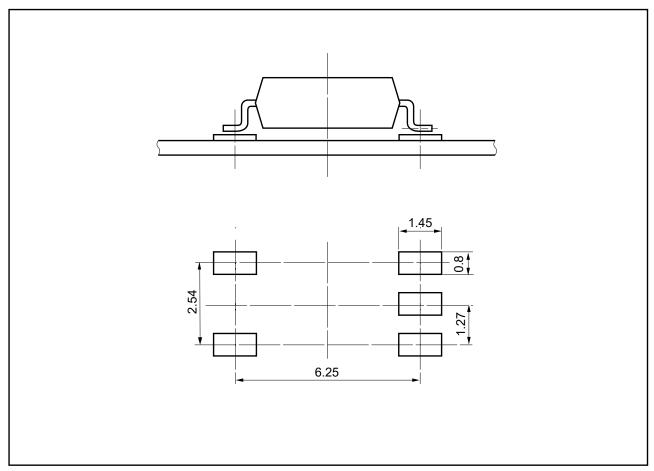


Outline and Dimensions (Reel)



Packing: 2 500 pcs/reel

RECOMMENDED MOUNT PAD DIMENSIONS (UNIT: mm)



[5pin SOP]

NOTES ON HANDLING

- 1. Recommended soldering conditions
 - (1) Infrared reflow soldering

· Peak reflow temperature 260°C or below (package surface temperature)

 Time of peak reflow temperature 10 seconds or less • Time of temperature higher than 220°C 60 seconds or less

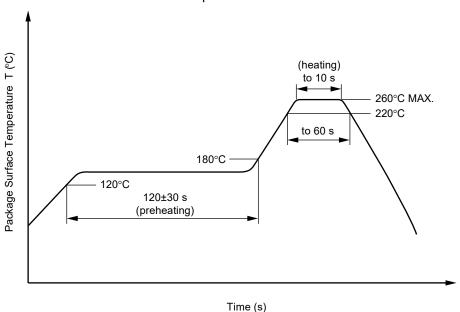
• Time to preheat temperature from 120 to 180°C 120±30 s

 Number of reflows Three

• Flux

Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

 Temperature 260°C or below (molten solder temperature)

 Time 10 seconds or less

 Preheating conditions 120°C or below (package surface temperature)

 Number of times One (Allowed to be dipped in solder including plastic mold portion.) • Flux Rosin flux containing small amount of chlorine (The flux with a maximum

chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by Soldering Iron

 Peak Temperature (lead part temperature) 350°C or below Time (each pins) 3 seconds or less

• Flux Rosin flux containing small amount of chlorine

(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
- (b) Please be sure that the temperature of the package would not be heated over 100°C
- (4) Cautions
 - Fluxes

Avoid removing the residual flux with freon-based and halogens-based (chlorine-based) cleaning solvent.

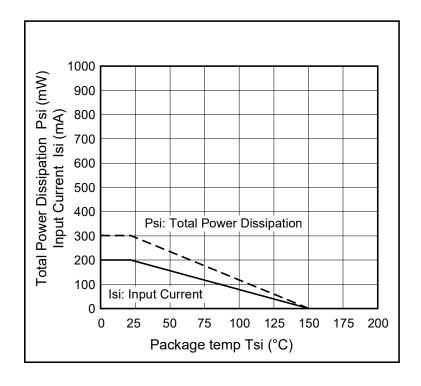
2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between V_{CC}-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

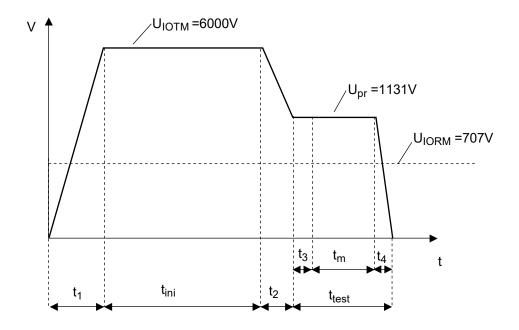
SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Rating	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength			
maximum operating isolation voltage	Ulorm	707	Vpeak
Test voltage (partial discharge test, procedure a for type test and random test)	Upr	1 131	V peak
$U_{pr} = 1.6 \times U_{IORM}, P_d < 5 pC$	Ο β.		• poun
Test voltage (partial discharge test, procedure b for all devices)	Upr	1 326	Vpeak
$U_{pr} = 1.875 \times U_{IORM}, P_d < 5 pC$	Орг	1 320	v peak
Highest permissible overvoltage	Uютм	6 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE 0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE 0110 Part 1)		III a	
Storage temperature range	Tstg	-55 to +125	°C
Operating temperature range	TA	-55 to +100	°C
Isolation resistance, minimum value			
V _{IO} = 500 V dc at T _A = 25°C	Ris MIN.	10 ¹²	Ω
V _{IO} = 500 V dc at T _A MAX. at least 100°C	Ris MIN.	10 ¹¹	Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal			
derating curve)			
Package temperature	Tsi	150	°C
Current (input current I _F , Psi = 0)	lsi	200	mA
Power (output or total power dissipation)	Psi	300	mW
Isolation resistance			
V _{IO} = 500 V dc at T _A = Tsi	Ris MIN.	10 ⁹	Ω

Dependence of maximum safety ratings with package temperature



Destructive Test, Type and Sample Test Method a)



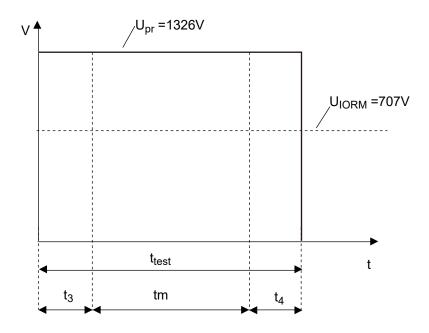
 $t_1, t_2 = 1 \text{ to } 10 \text{ sec}$

 $t_3, t_4 = 1 \text{ sec}$

 $t_{m(PARTIAL\ DISCHARGE)}$ = 10 sec t_{test} = 12 sec

 t_{ini} = 60 sec

Method b) Non-destructive Test, 100% Production Test



 $t_3, t_4 = 0.1 \text{ sec}$ $t_{m(PARTIAL\ DISCHARGE)}$ = 1.0 sec t_{test} = 1.2 sec

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or i any way allow it to enter the mouth.

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California Eastern Laboratories, Inc. 4590 Patrick Henry Drive, Santa Clara, California 95054-1817, U.S.A. Tel: +1-408-919-2500, Fax: +1-408-988-0279

Renesas Electronics Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-651-700, Fax: +44-1628-651-804

Renesas Electronics Europe GmbH Arcadiastrasse 10, 40472 Düsseldorf, Germany Tel: +49-211-6503-0, Fax: +49-211-6503-1327

Renesas Electronics (China) Co., Ltd.
Room 1709 Quantum Plaza, No.27 ZhichunLu, Haidian District, Beijing, 100191 P. R. China Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.
Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, 200333 P. R. China Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited
Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong Tel: +852-2265-6688, Fax: +852 2886-9022

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Renesas Electronics Malaysia Sdn.Bhd.
Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tei: +60-3-7955-9390, Fax: +60-3-7955-9301, Fax: +60-3-795-9301, Fax: +60-3-7955-9301, Fax: +60-3-7955-9301, Fax: +60-3-795-9301, Fax: +60-3-7955-9301, Fax: +60-3-795-9301, Fax: +60-3-795-9301, Fax: +60-3-795-9301, Fax: +60-3-795-9301, Fax: +6

Renesas Electronics India Pvt. Ltd. No.777C, 100 Feet Road, HAL 2nd Stage, Indiranagar, Bangalore 560 038, India Tel: +91-80-67208700, Fax: +91-80-67208777

Renesas Electronics Korea Co., Ltd.
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